

Bondline™ 6968 is a dielectric semiconductor grade die attach epoxy. This smooth consistency adhesive is non-tailing, non-bleeding and non-corrosive. It is ideal for auto dispensing, stamping, and screening. Excellent adhesion to copper, silver, and gold surfaces.

*“A Reliable
and Responsive
Adhesive
Company.”*

Adhesive Properties

Color:	Black
Viscosity*:	110,000 cps
Work Life @ 25°C:	24 hours
Hardness (Shore D):	90
Cure Options:	1 hour @ 150°C or 1 minute @ 175°C
Service Temperature Range:	-55°C to 200°C
Lap Shear Strength @ 25°C (Al to Al):	3500 psi
@ 25°C (Au to Au):	2500 psi
Mobile Ion Concentration:	
Fluoride:	ND
Chloride:	25ppm
Sodium:	3 ppm
Potassium:	ND
Specific Heat @150°C:	1.4 J/g K
Specific Gravity:	1.8
Thixotropic Index:	2.1
Glass Transition Temperature (Tg)**:	125°C
Weight Loss (TGA) @ 300°C:	1.30%
Coefficient of Thermal Expansion**:	
Below Tg:	24 x 10 ⁻⁶ in/in/°C
Above Tg:	67 x 10 ⁻⁶ in/in/°C
Shelf Life:	1 year @ -40°C or Colder
Availability:	Net volume 1cc to 10cc, available in disposable 3cc, 5cc & 10cc.

Adhesive properties are not intended to be used as specification limits.

* Brookfield DV II+, CP 51 Spindle, 2 rpm, 25°C

** Cured 1 hour @ 150°C

Bondline™

Electronic Adhesives, Inc.

756 N. Pastoria Avenue, Sunnyvale, CA 94085 USA
Phone: 408-830-9200 Fax: 408-830-9266 Website: www.bondline.net

Rev. 01/22/04

General Instructions for Adhesive Storage and Use

FROZEN STORAGE – Unless otherwise stated

This adhesive must be stored at (minus) –40°C (°F) or colder at all times. Storing this adhesive at temperatures warmer than (minus) –40°C (°F) may alter the adhesives' properties and shorten its work life. DO NOT RE-FREEZE adhesive that has already been thawed!

THAWING PROCESS

Adhesive must reach room temperature before use. Remove syringes from freezer. Place syringes on end for thawing. See chart below for thaw time based on syringe size.

SYRINGE SIZE	THAW TIME
1cc	5 minutes
3cc	10 minutes
5cc	15 minutes
10cc	20 minutes

**** NOTE:** To accelerate thaw time, place syringes in front of an air blower or fan. This will reduce the thaw time by approximately 50%. Remove all condensation from syringes prior to use.

SURFACE PREPARATION

Make sure that all surface areas to be bonded are free of any contamination. If parts have been solvent cleaned make sure solvent is dried before applying adhesive

APPLICATION

Check the work life of the adhesive, on the technical data sheet. Adhesives must be used within the work life time period. The adhesives' properties will change (usually thicken) if it is used past the allowable work life.

Apply adhesive using dispensing equipment of choice. Contact Bondline Technical Service with questions about dispensing adhesives.

CURE

Choose a Cure Option (time & temperature) from the Bondline technical data sheet. Preheat the oven to the temperature of the selected cure option. For optimum cure, do not deviate from the selected cure option. Be sure to allow additional time for holding fixtures to reach cure temperature. Avoid opening oven doors during cure. Large fixtures and/or multiple fixtures may require extended cure time.

SAFETY

Review the adhesive Material Safety Data Sheet (MSDS) before using. Refer to the MSDS in case of emergency. Always wear protective gloves and goggles while handling adhesives. Only work with adhesives in well-ventilated areas, with curing ovens vented outside. For industrial use only.

TECHNICAL SERVICE CONTACT

For recommendations and help with any aspect of adhesive applications please contact the Bondline Technical Service Department (408) 830-9200, or via email: info@bondline.net or visit our website, www.bondline.net

CAUTION: For industrial use only. People with sensitive skin may have a reaction to this adhesive. Avoid skin contact. Wash all areas with soap and water immediately if contact does occur. It is important to refer to Material Safety Data Sheet (MSDS) OSHA for more details.

Bondline™
Electronic Adhesives, Inc.

756 N. Pastoria Avenue, Sunnyvale, CA 94085 Phone: 408-830-9200 Fax: 408-830-9266 Website: www.bondline.net

© Bondline Electronic Adhesives, Inc. All rights reserved. All trademarks and registered trademarks belong to their respective owners. Notice to User: The information contained herein is based on technical data and tests which we believe reliable. It should be used by persons who have technical skill, at their own discretion and risk. Since conditions of use are outside of Bondline's control, we can assume no liability of results obtained or damages incurred through the application of data presented. Bondline's sole liability is limited to refund of purchase price of any product shown to be defective.